EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("5641559").PN. OR ("6399212").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/09/12 13:00
S1	1	JP-5185465-$.DID. OR JP-2000340928-$.DID.	US-PGPUB; USPAT; EPO; JPO;	ADJ	ON	2008/03/14 08:26
S2	1	10/511153	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:30
S3	559	printed circuit board and (wax or ink) and solving	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:33
S4	300	S3 and @pn<"20030411"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:34
S5	114	S4 and jet$	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:34
S6	47	S5 and etch$	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:36
S7	224	S3 and @pd<"20030411"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:41
S8	94	S7 and jet$	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:42
S9	35	S8 and etch$	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:42

S10	3	(method near printed circuit board) and (solv$ or dissolv?) and (ink or wax) resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:56
S11	3	(method near printed circuit board) and (solv$ or dissolv$) and (ink or wax) resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:57
S12	3	(method near printed near circuit near board) and (solv$ or dissolv$) and (ink or wax) resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:58
S13	1	(method near printed near board) and (solv$ or dissolv$) and (ink or wax) resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:59
S14	1	(method near printed near board) and (solv$ or dissolv$) and (ink or wax) near resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 08:59
S15	1	(method near printed near board) and (solv$ or dissolv$) and ((ink or wax) near2 resist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 09:00
S16	1551	method and (solv$ or dissolv$) and ((ink or wax) near2 resist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 09:01
S17	110	method and (solv$ or dissolv$) and ((ink or wax) near2 resist) and (printed near board)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 09:02
S18	1	((solv$ or dissolv$) and ((wax) near2 resist) and (printed near board)) not S17	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 09:23
S19	3	((solv$ or dissolv$) and ((wax or hydrocarbon) near2 resist) and (printed near board))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 09:24

S20	2	("3,053,215").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/14 09:27
S21	1	JP-5185465-$.DID. OR JP-8288619-$.DID. OR JP-2000340928-$.DID.	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/03/14 09:45
S22	1113	(printed near board) and etch$ and additive	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 09:55
S23	46	S22 and ((ink or wax) near resist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 09:56
S24	518	S22 and @pd<"20030411"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 09:58
S25	2	"3146125".PN.	USPAT; USOCR	ADJ	ON	2008/03/14 10:03
S26	2	"3573973".PN.	USPAT; USOCR	ADJ	ON	2008/03/14 10:04
S27	2	"3600330".PN.	USPAT; USOCR	ADJ	ON	2008/03/14 10:06
S28	1	("4720798").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/14 10:35
S29	5	(("4720798") or ("3053215") or ("3573973")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/14 10:36
S30	0	("additiveand (printednearboard)and ((inkorwax)nearresist) andjet$").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/14 10:42
S31	7	additive and (printed near board) and ((ink or wax) near resist) and jet$	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 10:43
S32	32	additive and (printed near board) and ((ink or wax) near resist) and (jet$ or spray$)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 10:44
S33	1	"4943516".PN.	USPAT; USOCR	ADJ	ON	2008/03/14 10:46
S34	1	"5554670".PN.	USPAT; USOCR	ADJ	ON	2008/03/14 10:48

S35	1	"5665526".PN.	USPAT; USOCR	ADJ	ON	2008/03/14 10:48
S36	1	"5830528".PN.	USPAT; USOCR	ADJ	ON	2008/03/14 10:48
S37	1	"5858618".PN.	USPAT; USOCR	ADJ	ON	2008/03/14 10:48
S38	17	("3573973").URPN.	USPAT	ADJ	ON	2008/03/14 10:56
S39	22	(("3,537,507") or ("3,244,553") or ("1,582,668") or ("3,415,679") or ("3,269,861") or ("3,245,826") or ("3,212,918") or ("3,135,638") or ("3,115,423") or ("3,035,916") or ("3,006,819")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/14 11:03
S40	1	("4720798").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/17 08:52
S41	2	"5185465"	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/09/04 15:36
S42	332	negative resist and (inkjet or inkjet) and wax	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 13:21
S43	10	S42 and circuit board	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 13:22
S44	2	(wax with resist with (inkjet or inkjet))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 13:23
S45	4	(wax with resist with (inkjet or ink jet))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 13:23
S46	28	(wax with mask with (inkjet or ink jet))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 13:26

S47	317	(427/97.5).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/11 13:40
S48	19	S47 and wax	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 13:40
S49	4	("2003/0203101").URPN.	USPAT	ADJ	ON	2008/09/11 14:58
S50	3117	negative with (resist or mask or image) and wax	USPAT	ADJ	ON	2008/09/11 15:10
S51	251	negative with (resist or mask or image) and wax and circuit board	USPAT	ADJ	ON	2008/09/11 15:10
S52	407	negative with (resist or mask or image) and wax and circuit board	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 15:11
S53	241	negative with (resist or mask) and wax and circuit board	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 15:12
S54	44	negative with (resist or mask) and wax and circuit board and (inkjet or ink jet)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 15:15
S55	2	("6972261").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/11 15:26
S56	2	("5,685,491").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/11 15:30

S57	4	("3841261").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/11 15:59
S58	1	(remov$ with oil) and offset drum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 16:12
S59	0	(oil) same offset drum same ozone	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 16:17
S60	4	(oil) same offset drum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 16:17
S61	0	flexible with (circuit board or pcb) and (oil same drum same ozone)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 16:19
S62	4	flexible with (circuit board or pcb) and (oil same drum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 16:19
S63	27	flexible with (circuit board or pcb) and (offset with drum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 16:27
S64	3	flexible with (circuit board or pcb) and (ozone with oil)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 16:30
S65	3	flexible with (circuit board or pcb) and (oil with ozone)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/11 16:36
S66	4	2003/0203101	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/09/12 10:55

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USPAT; EPO;
JPO;
DERWENT;
IBM_TDB | ADJ | ON | 2008/09/12
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